

In the Claims

Claim 1 (original): A semiconductor package comprising a solder having an alpha flux of less than 0.001 cts/cm²/hr.

Claim 2 (original): The semiconductor package of claim 1 wherein the solder predominately comprises Ag, Bi, Cu, In, Pb or Sn.

Claim 3 (original): The semiconductor package of claim 1 wherein the solder predominately comprises Ag.

Claim 4 (original): The semiconductor package of claim 1 wherein the solder predominately comprises Sn.

Claim 5 (original): The semiconductor package of claim 1 wherein the solder is substantially lead-free.

Claim 6 (original): The semiconductor package of claim 1 wherein the solder is lead-containing solder that is at least 99 weight% lead.

Claim 7 (original): The semiconductor package of claim 6 wherein the lead-containing solder has an alpha flux of less than 0.0005 cts/cm²/hr.

Claim 8 (original): The semiconductor package of claim 6 wherein the lead-containing solder has an alpha flux of less than $0.0002 \text{ cts/cm}^2/\text{hr}$.

Claim 9 (original): The semiconductor package of claim 6 wherein the lead-containing solder has an alpha flux of less than $0.0001 \text{ cts/cm}^2/\text{hr}$.

Claim 10 (original): A lead-containing anode having an alpha flux of less than $0.001 \text{ cts/cm}^2/\text{hr}$, the lead-containing anode comprising at least about 50 weight% lead.

Claim 11 (original): The lead-containing anode of claim 10 having an alpha flux of less than $0.0005 \text{ cts/cm}^2/\text{hr}$.

Claim 12 (original): The lead-containing anode of claim 10 having an alpha flux of less than $0.0002 \text{ cts/cm}^2/\text{hr}$.

Claim 13 (original): The lead-containing anode of claim 10 having an alpha flux of less than $0.0001 \text{ cts/cm}^2/\text{hr}$.

Claim 14 (original): A lead-containing solder bump having an alpha flux of less than $0.001 \text{ cts/cm}^2/\text{hr}$, the lead-containing solder bump comprising at least about 50 weight% lead.

Claim 15 (original): The lead-containing solder bump of claim 14 having an alpha flux of less than 0.0005 cts/cm²/hr.

Claim 16 (original): The lead-containing solder bump of claim 14 having an alpha flux of less than 0.0002 cts/cm²/hr.

Claim 17 (original): The lead-containing solder bump of claim 14 having an alpha flux of less than 0.0001 cts/cm²/hr.

Claim 18 (original): A lead-containing solder paste having an alpha flux of less than 0.001 cts/cm²/hr, the lead-containing solder paste comprising at least about 50 weight% lead.

Claim 19 (original): The solder paste of claim 18 having an alpha flux of less than 0.0005 cts/cm²/hr.

Claim 20 (original): The solder paste of claim 18 having an alpha flux of less than 0.0002 cts/cm²/hr.

Claim 21 (original): The solder paste of claim 18 having an alpha flux of less than 0.0001 cts/cm²/hr.

Claims 22-29 (canceled).